

From: rahaman@fnal.gov
To: Joel Goldstein <joelg@fnal.gov>
CC: Bolla Gino <bolla@physics.purdue.edu>
Date: Mon, October 21, 2002 4:38 pm
Subject: Re: Status of Oven Test

Hi,

The board is ready with the back side wire-bonding.
Now the front side wire-bonding is pending tomorrow
morning. The continuity test will be done after that.

I wanted to do the continuity test before bonding but
Bert suggested to do it afterward because then its easy
plus doing it before could make scratch on the bond-pad.

I hope by tomorrow things will be ready and then from
day-after-tomorrow we can start the real expt.

do you have some time tomorrow after-noon
to set up the expt. I have the power suply
0-30V already.

cheers,
Azizur

cheers,
Azizur

Azizur RAHAMAN
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----- Original Message -----

From: Joel Goldstein <joelg@fnal.gov>
Date: Monday, October 21, 2002 12:01 pm
Subject: Status of Oven Test

> Hi Azizur,
>
> How are the preparations for the aging test going? Is the board ready?
> Have you tested the continuity of the jumpers?
>
> Let me know how things stand.
>
> Joel
>
>
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